



Material Composition Declaration

EPC2010C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	10.5 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	9.1182	86.62	89.09	866208
	Silicon oxide	7631-86-9	0.0349	0.33		3315
	Silicon nitride	12033-89-5	0.0108	0.10		1031
	Gallium nitride	25617-97-4	0.0662	0.63		6293
	Aluminum	7429-90-5	0.0683	0.65		6484
	Aluminum nitride	24304-00-5	0.0163	0.15		1546
	Titanium	7440-32-6	0.0013	0.01		124
	Titanium nitride	25583-20-4	0.0058	0.05		548
	Copper	7440-50-8	0.0023	0.02		216
	Tungsten	7440-33-7	0.0013	0.01		121
	Polyimide		0.0525	0.50		4986
Under Bump Metal	Titanium	7440-32-6	0.0017	0.02	1.39	165
	Nickel	7440-02-0	0.0514	0.49		4883
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0931	0.88		8842
Solder Bump	Tin	7440-31-5	0.9775	9.29	9.52	92857
	Silver	7440-22-4	0.0251	0.24		2381
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			10.5	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.